**FABRICATION INSTRUCTIONS**

QTY – 6 BOARDS

TOTAL LAYERS – **4**

OVERALL THICKNESS – **0.062” +/- 10%** FR-4

FINISHED COPPER WEIGHT **– 1.5 ounce for top and bottom layers, 1 ounce for inner layers.**

SURFACE FINISH -- **ENIG**

SOLDERMASK COLOR-- GREEN

LEGEND COLOR – WHITE

FABRICATION NOTES: UNLESS OTHERWISE SPECIFIED OR PRE-APPROVED

1. MILLIMETER DIMENSIONS (MM) ARE THE CONTROLLING DIMENSIONS FOR THE DRAWING(S) AND SUPPLIED DATA
2. FINISHED THICKNESS INCLUDES SOLDER-MASK.
3. THIS DESIGN CONTAINS DIFFERENTIAL PAIR TRACES.

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| --- | --- | --- | --- | --- |
| 1. **Layer** | **Type** | **Impedance** | **Width** | **Spacing** |
| Bottom Layer | Microstrip | 90 Ohm | 10 mil | 10 mil |

1. LAYER STACKUP. INDIVIDUAL LAYER THICKNESS MAY BE PROPOSED AND ADJUSTED BY MANUFACTURER.

|  |  |  |  |  |
| --- | --- | --- | --- | --- |
|  | Overlay | Material | Thickness (mil) | Dielectric Material |
| Top Overlay | Overlay |  |  |  |
| Top Solder | Solder Mask/Coverlay | SurfaceMaterial | 0.7 | Solder Resist |
| Top Layer | Signal | Copper | 1.4 |  |
| Dielectric 1 | Dielectric | Prepreg | 7.5 | FR-4 |
| GND | Internal Plane | Copper | 1.4 |  |
| Dielectric 2 | Dielectric | Core | 40 | FR-4 |
| PWR | Signal | Copper | 1.4 |  |
| Dielectric 3 | Dielectric | Prepeg | 7.5 | FR-4 |
| Bottom Layer | Signal | Copper | 1.4 |  |
| Bottom Solder | Solder Mask/Coverlay | SurfaceMaterial | 0.7 | Solder Resist |
| Bottom Overlay | Overlay |  |  |  |

TOTAL: 62 MIL